

WHAT IS CLAIMED IS:

1. A housing for electronic equipment comprising:
  - a metal base board having at least one through holes;
  - one or more components that are joined to the metal base board by outsert-molding; and
  - one or more side walls in which said metal base board and said one or more components are joined, wherein at least one part of a terminal part of said metal base board <sup>at</sup> one or more side walls is formed in a convex shape which is not joined to said components.
2. A housing for electronic equipment comprising:
  - a metal base board;
  - one or more components that are joined to the metal base board by outsert-molding; and
  - one or more side walls in which said metal base board and said one or more components are joined, wherein at least one part of a terminal part of said metal base board <sup>at</sup> one or more side walls is formed in a concave shape.
3. A housing for electronic equipment comprising:
  - a metal base board; and
  - one or more components that are joined to the metal base board by outsert-molding; and

two or more side walls in which at least one part of said metal base board is joined with said components,

wherein at least one corner formed by two of said two or more side walls, said metal base boards forming said two side walls are not partially or entirely in contact with each other.

4. A housing for electronic equipment comprising:

a metal base board;

one or more components that are joined to the metal base board by outsert-molding; and

a side wall,

wherein said components are joined to whole of one surface of said metal base board except for at least the side wall, and a ratio of thickness of said metal base board to a total thickness of the housing is in a range of 1% to 5%.

5. A housing for electronic equipment comprising:

a metal base board;

one or more components that are joined to the metal base board by outsert-molding; and

a side wall,

wherein said components are joined to whole of one surface of said metal base board except for at least the side wall, and a ratio of thickness of said metal base board to total thickness of the housing is

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in a range of 8% to 12%.

6. A housing for electronic equipment comprising:

a metal base board;

one or more components that are joined to the metal base board by outsert-molding; and

a side wall,

wherein said components are joined to whole of one surface of said metal base board except for at least the side wall, and a ratio of thickness of said metal base board to total thickness of the housing is in a range of 30% to 50%.

7. The housing for electronic equipment according to claim 1, wherein a development shape of said metal base board has at least one through hole, and has a notch of an arbitrary angle at one or more corners of the development shape.

8. The housing for electronic equipment according to claim 6, wherein a development shape of said metal base board has at least one through hole, and has a notch of an arbitrary angle at one or more corners of the development shape.

9. The housing for electronic equipment according to claim 1, wherein on a surface of said component attached on said metal base board, said component is formed in a concave shape at at least one of portions corresponding to said through holes of said metal base board.

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10. A manufacturing method of a housing for electronic equipment including a metal base board and one or more components that are joined to the metal base board by outsert-molding, comprising the steps of:

~~forming said components on a surface of said metal base board opposite to a gate for the outsert-molding by synthetic resin injection from the gate provided at a position where synthetic resin can be injected through at least one through hole of said base board; and~~

bending and processing side walls of the housing by pressure of injection of synthetic resin.

11. A manufacturing method of a housing for electronic equipment including a metal base board and one or more components that are joined to the metal base board by outsert-molding,

wherein as a method of fixing said metal base board to a die when forming said components on a surface of the metal base board opposite to a gate for the outsert-molding by synthetic resin injection from the gate provided at a position where synthetic resin can be injected through at least one through hole of said metal base board, a positioning pin is provided to at least one of said through holes.

12. The manufacturing method of a housing for electronic equipment according to claim 11,

wherein vacuum-pull is used for fixing said base board onto the die.

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13. Electronic equipment comprising a housing for  
electronic equipment according to claim 1.

